

This high performance silicone can be packaged in pre-measured BIPAX and FLXPAX kits for easy handling and storage.

Note: All values shown are TYPICAL. Because the conditions of use are beyond our control and can significantly affect the results obtained from the materials listed above, all recommendations and suggestions are made without any guarantees or warranties whatsoever.

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TRA-BOND 2151 epoxy - yes 7.23.02 called
Customer Service

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<% dim userID dim extendURL userID = Request.QueryString("msscuid") if userID <> "" then
  extendURL = "&msscuid=" & userID else extendURL = "" end if %>
```



GENERAL PURPOSE

CASTING

MEDICAL PHOTONICS ELECTRONICS

PASTE

UV CURING

APPLICATIONS

Advanced Polymers for Electronics

Known for developing high reliability special formulations for demanding applications, TRA-CON has a proven line of thermally and electrically conductive epoxies and silicones. TRA-CON products are designed to provide reliable component protection in applications such as heat sink bonding, solderless connections, die attach adhesives and surface mount. They are designed to meet the challenges of heat dissipation that result from increasing line densities and shrinking geometries such as wireless communications, satellite transmission and circuit board manufacturing.

Download this Electronics Applications Guide Brochure with Technical Data Sheets.

Component Protection

Characteristics	1 Part	High Operating Temp	Room Temp Cure	Flexible	Fast Cure
	Supratherm 81GH01	TRA-BOND 2254	TRA-BOND 2151	TRA-BOND 2156	TRA-BOND 2156
Thermal Conductivity (cal-cm/cm ² sec°C)	48 x 10(-4)	24 x 10(-4)	21 x 10(-4)	20 x 10(-4)	20 x 10(-4)
Cure Time	24 hrs @ 25°C or 2 hrs @ 65°C	2 hrs @ 65°C plus 2 hrs @ 100°C	24 hrs @ 25°C or 2 hrs @ 65°C	24 hrs @ 25°C or 2 hrs @ 65°C	2 hrs @ 25°C
Shore D Hardness	80	97	90	60	80
Viscosity (cps @ 10 rpm)	5000	66,000	35,000	35,000	50,000
Thixotropic Index (5 rpm/50 rpm)	1.7	1.9	2	2.9	1.1
Operating Temp (°C)	-70 to 115	-70 to 205	-70 to 115	-70 to 125	-70 to 100
Work Life	45 minutes	3 hours	45 minutes	3 hours	5 minutes
	TRA-DUCT 2902	TRA-DUCT 2907	TRA-DUCT 2929	TRA-DUCT 2958	TRA-DUCT 2924
Volume Resistivity (ohm-cm)	0.001	0.001	0.001	0.0004	0.0005
Cure Time	24 hrs @ 25°C or 2 hrs @ 65°C	2 hrs @ 65°C plus 2 hrs @ 100°C	24 hrs @ 25°C or 2 hrs @ 65°C	24 hrs @ 25°C or 2 hrs @ 65°C	2 hrs @ 25°C
Shore D Hardness	85	85	82A	80	89
Viscosity (cps @ 10 rpm)	24,000	7000	70,000	40,000	15,000
Thixotropic Index (5 rpm/50 rpm)	3.75	3.52	2.2	2.9	2.7
Operating Temp (°C)	-60 to 110	-60 to 110	-60 to 110	-55 to 175	-60 to 205
Work Life	1 hour	3 hours	3 hours	4 hours	8 hours
	TRA-BOND 2222	TRA-CAST 3143	TRA-CAST 3145	TRA-CAST 3010	TRA-CAST 3103
Cure Time	15 min @ 100°C	24 hrs @ 25°C or 2 hrs @ 65°C	24 hrs @ 25°C or 2 hrs @ 65°C	96 hrs @ 25°C	24 hrs @ 25°C or 2 hrs @ 65°C
Shore D Hardness	85	78	90	20D/65A	85
Viscosity (cps @ 10 rpm)	150,000	400	18,800	400	5600
Thixotropic Index (5 rpm/50 rpm)	3.3	1.2	1.1	1	1.3
Operating Temp (°C)	-50 to 125	-70 to 100	-60 to 140	-60 to 105	-60 to 145
Work Life	3 months @ 20°C	3 hours	1 hour	24 hours	30 minutes

TRA-BOND 813J01

High Temperature Thermally Conductive Silicone

TRA-BOND 813J01 was specifically designed as a high temperature, flexible, thermally conductive product for the encapsulation of heat-generating devices and modules such as transformers, rectifiers, thermistors, and power supplies. The material can be cured over a wide range of temperatures and once cured can operate at temperatures up to 260°C.

TRA-BOND 813J01, a highly filled material exhibits superior thermal characteristics and is perfect for applications that require thermal management. The flexibility of the material also lends itself to applications where dissimilar substrates must be bonded.